Wire Bond Trade Off Cost Model

The Wire Bond Trade Off Cost Model is designed with a simple philosophy: Maximize the number of optional inputs while minimizing the number of required inputs. This tool allows customers to use the same model early in the design with a few parameters compared with later in the design when all the package details are known. The model is a result of a joint project between TechSearch International, Inc., the leading market research firm in semiconductor packaging and assembly trends, and SavanSys Solutions LLC, the leader in electronic manufacturing cost modeling. This model is a comprehensive activity based model including die preparation, substrate fabrication, and package assembly and its accuracy has been validated using dozens of industry data points.

Use the estimator to:

- Accurately quantify the cost of technology choices—layer count, package size, design rules, materials, etc.
- Compare the cost trade-off between copper versus gold wire bonding
- Trade off manufacturing locations for assembly and substrate fabrication

Choose the best location to optimize your cost:

- Obtain the "should cost" value for your package
- Understand and manage your detailed costs—labor, material, capital, tooling, and yield impacts—for every step in the substrate fabrication and assembly process

An optional enhancement is to create a model calibrated to a specific supplier (internal or external). Our team of professionals can work with you to calibrate the model or work directly with the supplier to create a supplier certified model.

The list of model parameters is as follows:

Manufacturing location/labor rate
Lot size
Annual/lifetime volume
Wafer probe yield
Factory utilization
Cost of gold
Panel length/width
Package size
Package I/O count
Substrate structure
Die length/width/thickness
Die cost
Die pad pitch
Wire material
2D wire length
Looping factor
Wire diameter
Line and via design rules
Core material
Core thickness
BGA pitch
Wire bond count
Microvia count
PTH count
Heat spreader
Mold compound
Surface finish
Fabrication process
Strip length/width
Allocated overhead/profit

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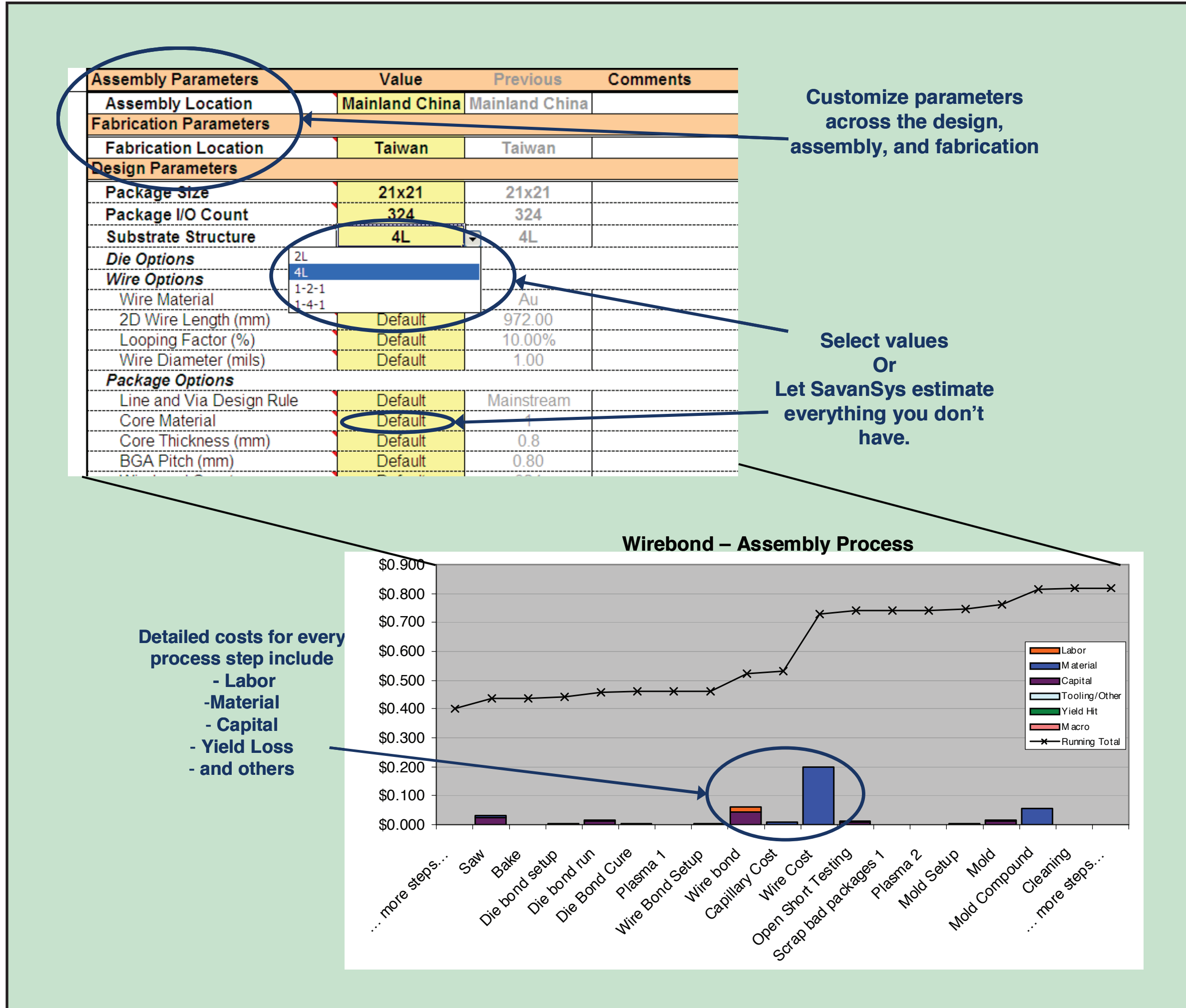

Fax to 512-372-8889 or Email to tsi@techsearchinc.com

Name: ______________________ Email: ______________________

Position: ______________________ Telephone: ______________________

Company: ______________________ Fax: ______________________

Ship to Address: ______________________ Bill to Address: ______________________

Purchase Order Number: ______________________

AMEX, Visa, MC, JCB: ______________________ Exp. Date: ____________

Annual Model Price: $ $2,500.00

Total Amount: $______________

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